GT90

Soft and Elastic Graphene Enhanced Thermal Interface Material

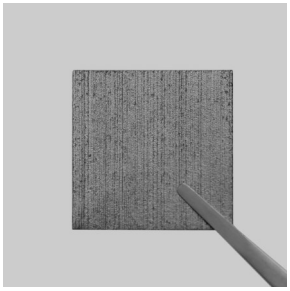
Trademark: GT-TIM

Features:

- Extremely High Thermal Conductivity
- Low Effective Thermal Resistance
- High Compressibilty and Ultra Light

Applications:

Thermal Burn-In, IC thermal testing, 5G devices, automotive electronics GPU, CPU, RF, Opto module, IGBT, LED and other power modules cooling



Description:

GT90 is a very soft graphene enhanced thermal Interface material. It has extremely low effective thermal resistance (6.7 Kmm^2 / W at 275 KPa). Moreover, the GT90 has advantages of low density, high recovery and good softness. GT90 opens new opportunities for addressing large heat dissipation issues in thermal burn-in, IC thermal testing, electronics and other high power driven systems.

Physical Properties	Value	Units	Test Method
Bulk Thermal Conductivity	90 ± 10 (275KPa, 300μm)	W / mK	ASTM5470
Effective Thermal Resistance	6.7 ± 0.5 (275KPa, 300μm)	Kmm^2 / W	ASTM5470
Thickness Range for Production	0.2 - 2	mm	Micrometer
Thickness Tolerance	< 10	%	Micrometer
Pad Size	Up to 60 * 60	mm	-
Compressibility	> 50	%	-
Compressive Strength	690 ± 50 (300μm)	KPa	At 50% compression
Recovery	> 70	%	-
Tensile Strength	> 50 ± 20	KPa	Tensile tester
Surface Roughness (Ra)	5 ± 3	μm	Wyko NT1100 optical profilometer
Surface Roughness (Rz)	30 ± 15	μm	Wyko NT1100 optical profilometer
Application Temperature	-40 to 200	°C	-
Flammability	V - 0		UL94
Specific Heat	0.25 ± 0.05	J / g.K	Hotdisk
Density	0.43 ± 0.03	g / cm^3	Balance and Micrometer
Color	Grey	-	Visual

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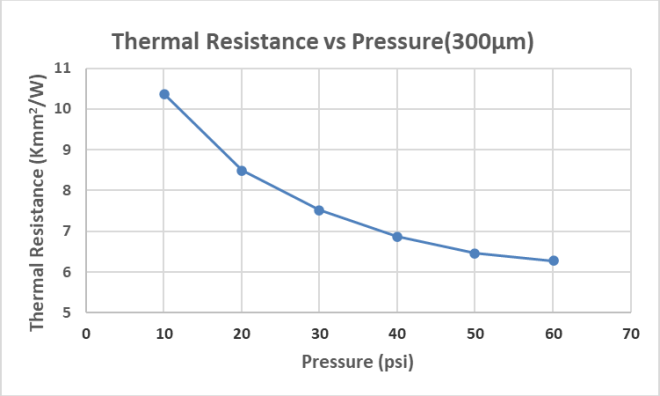
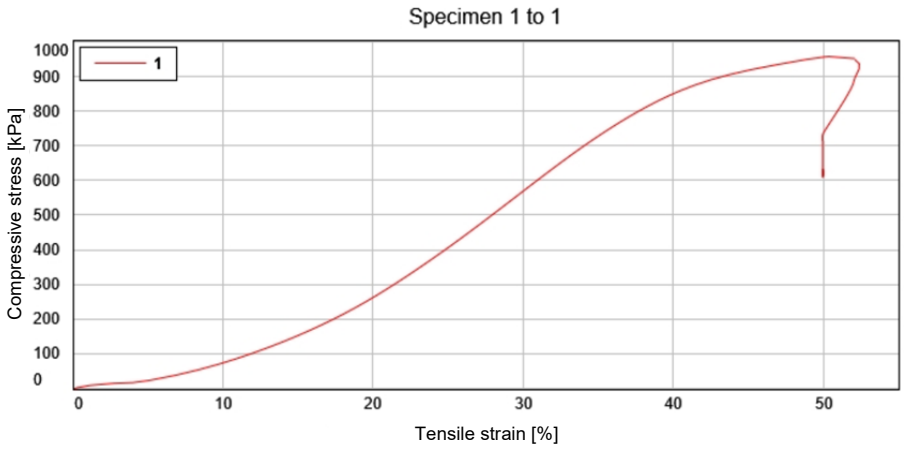
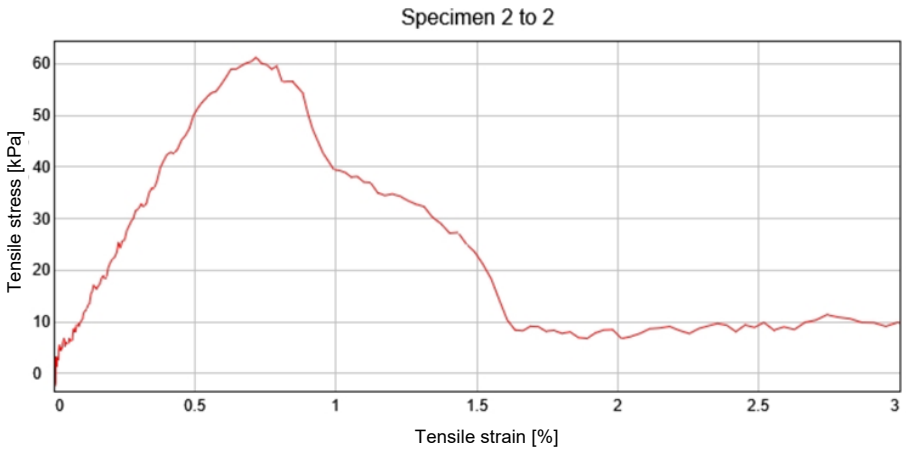


Compressive Stress vs Strain Curve at 50% compression (300µm)



Tensile Strength



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